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FOR IMMEDIATE RELEASE

HDP User Group Announces New Member Company

Cave Creek, Arizona May 27, 2013. The High Density Packaging (HDP) User Group headquartered in the United States announces that Engent, Inc. has become its newest member.

Engent, Inc. is a market leader in providing advanced, leading edge electronics and microelectronics packaging development and production services to customers seeking next generation capabilities. With industry-unique packaging and interconnect expertise and a world-class facility, Engent provides a turnkey service offering to its clients, including:

- Production of microelectronic, MEMS and system in package (SIP) assemblies
- Prototyping & production ramp-to-volume
- Semiconductor packaging development & new product introduction
- Semiconductor packaging qualification
- Reliability testing

Engent provides solutions in advanced electronics production, product design for manufacture, and assembly processes.

Dan Baldwin, Engent President said "We are very excited to participate in the HDP User Group. We see immense value in participating in pre-competitive research and development as a means to continually expand our packaging technology toolbox and enable our customers to launch and produce their next generation products. Engent is looking forward to working with the like-minded members of the HDP User Group to advance the fundamentals of next generation packaging and materials technologies."

Marshall Andrews Executive Director of HDP User Group said "We are pleased that Engent, an innovative new EMS provider has joined our consortium. They will be participating in several HDP projects. Including TSV which is focused on understanding second level reliability and thermal dissipation of 3D packaged components, and Opto Electronics which is addressing performance limitations encountered in high-speed electrical backplanes (15-20+ Gbps) by use of optical signal transmission."

About Engent

Engent, Inc. (www.engentaat.com) is a leading provider of next generation microelectronics development and manufacturing services. Located in Norcross, GA, Engent was founded in 2003 to provide world class production, development and qualification services for small form factor electronics. Engent engages in all stages of the electronic miniaturization process and serves key microelectronic markets in the military, medical and industrial sectors with clients ranging from budding entrepreneurial technology firms to Fortune 50 companies.

Learn more @ www.engentaat.com or follow us on Linked-in

About HDP User Group

HDP User Group (www.hdpug.org) is a global research and development organization based in Cave Creek Arizona, is dedicated to "reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly". This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas; Stockholm, Sweden; and Tokyo, Japan.

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963